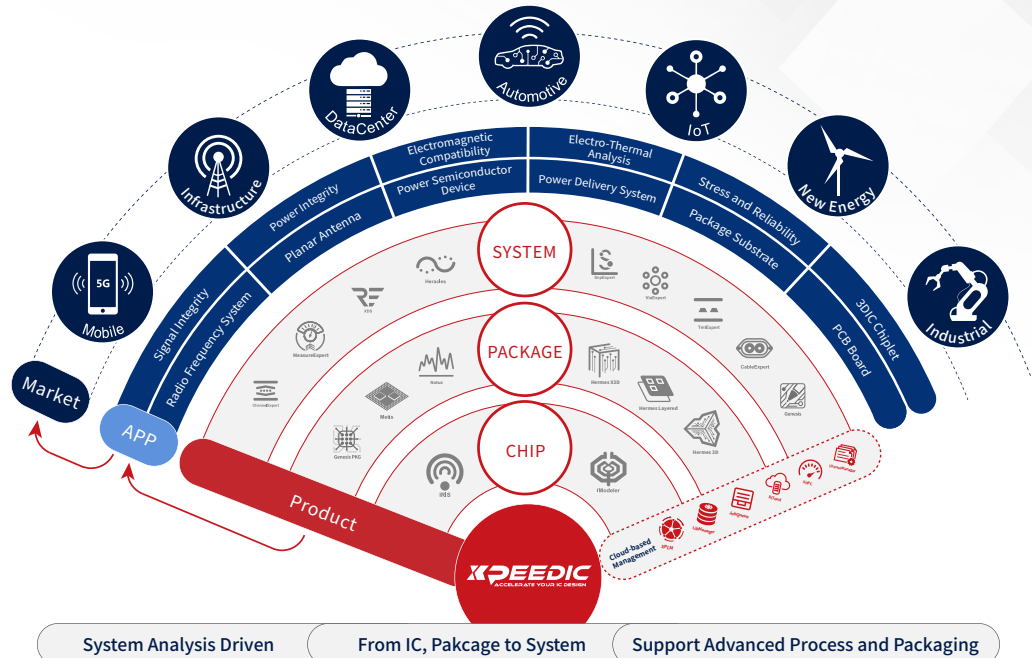


# Xpeedic Simulation EDA for IC-Package-System



## Xpeedic EDA Overview

Support advanced process and packaging to enable next-generation integrated system



## Xpeedic EDA Product Family

To enable next generation intelligent electronic system

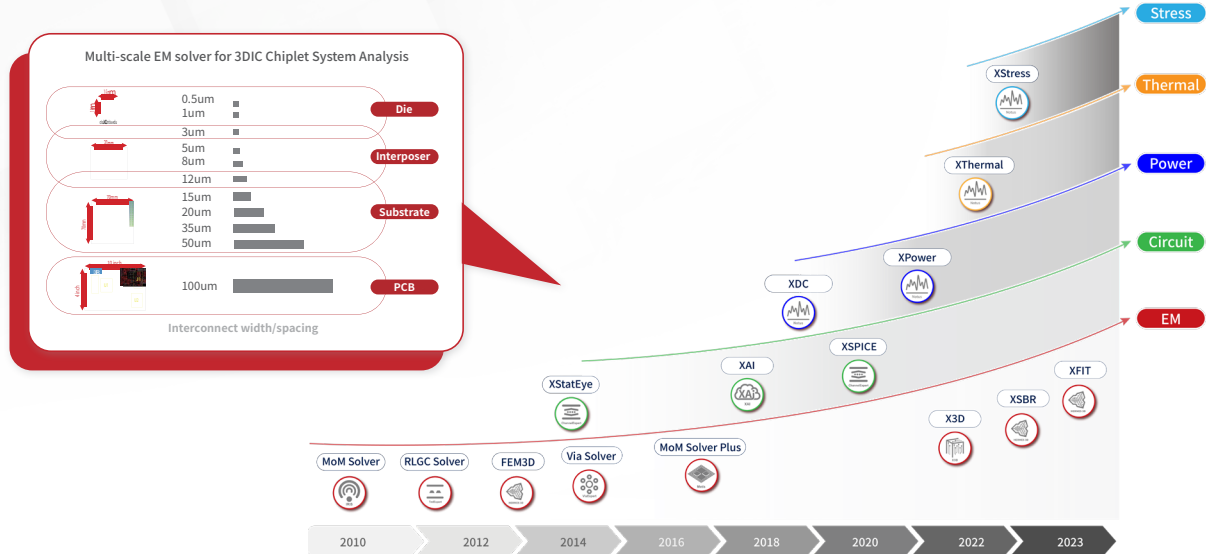


# Xpeedic EDA Core Technologies

1

## Industry Leading Solver Technology

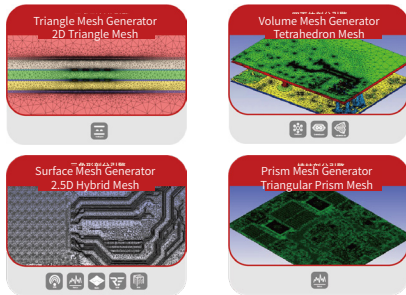
Multi physics solver technology from circuit, electromagnetic, thermal to stress simulation



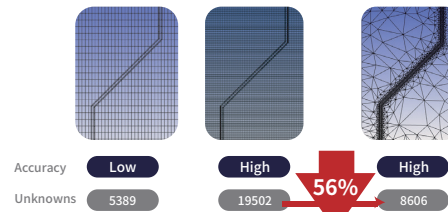
2

## AI-based Mesh Technology

Multiple Adaptive Mesh Technology For Different Application Scenarios



Convergent Results With Minimum Number Of Mesh Elements

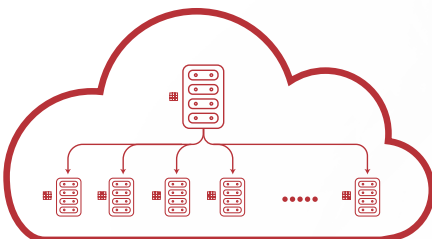


Auto Mesh Tunneling Technique

3

## High Performance Distributed Parallel Computing Technology

Matrix-level Distributed Parallel Computing By MPI



Success Cases: Use Metis for Advanced Packaging Simulation  
Result: Metis delivers 10X simulation speed comparing to the other tools.

